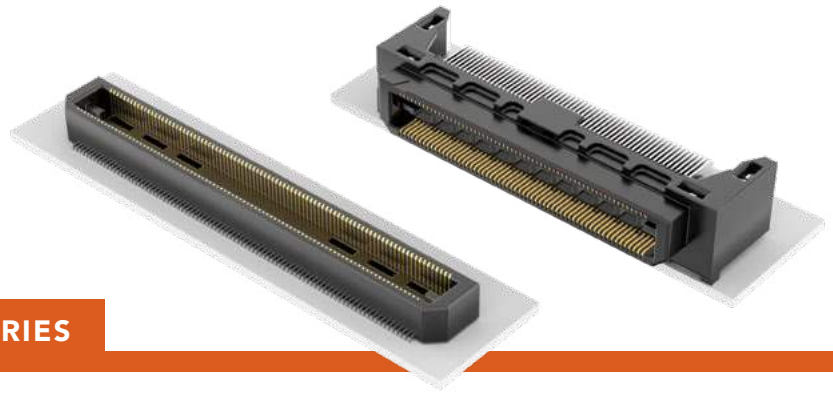


BASIC BLADE & BEAM HEADER

(0.50 mm) .0197" PITCH • BTH SERIES



BTH

Mates:
BSH

SPECIFICATIONS

Insulator Material:

Black LCP

Contact Material:

Phosphor Bronze

Plating:

Au or Sn over
50 μ" (1.27 μm) Ni

Current Rating:

2.0 A per pin
(2 pins powered)

Operating Temp Range:

-55 °C to +125 °C

Voltage Rating:

175 VAC

Max Cycles:

100

PROCESSING

Lead-Free Solderable:

Yes

SMT Lead Coplanarity:

Vertical=
(0.10 mm) .004" max (030-090),
(0.15 mm) .006" max (120-150)*
Right-angle=
(0.15 mm) .006" max (030-090)*
*(.004" stencil solution
may be available; contact
IPG@samtec.com)

Board Stacking:

For applications requiring more
than two connectors per board
or 90 positions or higher,
contact ipg@samtec.com

ALSO AVAILABLE

MOQ Required

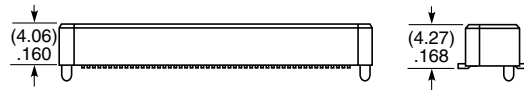
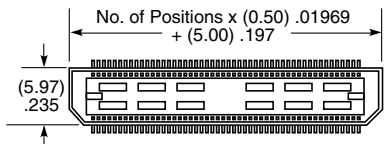
30 μ" (0.76 μm) Gold
Edge Mount Capability
8 mm, 11 mm, 16 mm,
19 mm and 22 mm Stack
Height (Caution: Some
automatic placement/
inspection machines may
have component height
restrictions. Please consult
machinery specifications.)
(11 mm, 16 mm, 19 mm
and 22 mm not available
with 50 positions)



Note:

Some lengths, styles and
options are non-standard,
non-returnable.

BTH	NO. OF POSITIONS PER ROW	01	PLATING OPTION	D	A	OTHER OPTION
	-030, -050, -060, -090, -120, -150		<p>-F = Gold Flash on contact, Matte Tin on tail</p> <p>-L = 10 μ" (0.25 μm) Gold on contact, Matte Tin on tail</p> <p>-C* = Electro-Polished Selective 50 μ" (1.27 μm) min Au over 150 μ" (3.81 μm) Ni on Signal Pins in contact area, Matte Tin over 50 μ" (1.27 μm) min Ni on all solder tails (*-C Plating passes 10 year MFG testing)</p>			<p>-K = (7.00 mm) .276" DIA Polyimide Film Pick & Place Pad</p> <p>-TR = Tape & Reel (120 positions maximum)</p> <p>-FR = Full Reel Tape & Reel (must order maximum quantity per reel; contact Samtec for quantity breaks) (120 positions maximum)</p>



MATED HEIGHT

LEAD STYLE	MATED HEIGHT*
-01	(5.00 mm) .1971"

*Processing conditions will affect mated height.

BTH	NO. OF POSITIONS PER ROW	01	PLATING OPTION	D	RA	WT	OTHER OPTION
	-030, -060, -090		<p>-F = Gold Flash on contact, Matte Tin on tail</p> <p>-L = 10 μ" (0.25 μm) Gold on contact, Matte Tin on tail</p>				<p>-K = (7.00 mm) .276" DIA Polyimide Film Pick & Place Pad</p>

